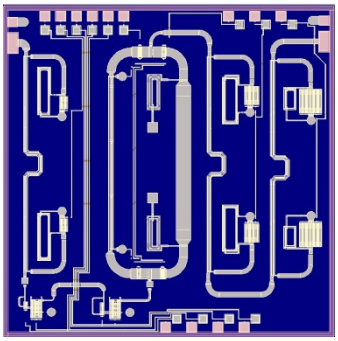
TGP2107

6 to 18 GHz 6-Bit Digital Phase Shifter (-V_c)

Applications

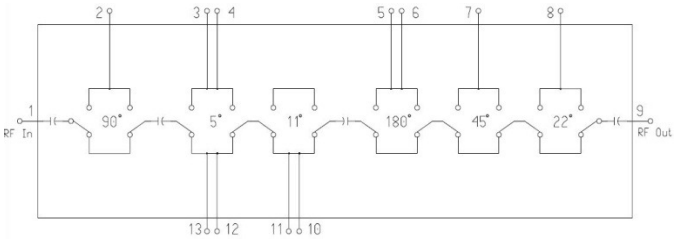
- Phased Array Antenna Systems
- Satellite Communication Systems
- Electronic Warfare



Product Features

- Frequency Range: 6 to 18 GHz
- 6-Bit Digital Phase Shifter
- 360° Coverage, LSB = 5.625°
- RMS Phase Error: 5°
- RMS Amplitude Error: 0.55 dB
- Insertion Loss: <10 dB
- Return Loss: >12 dB
- Input P1dB: >25 dBm
- Input IP3: >41 dBm
- Control Voltage: –5/0 V
- Chip Dimensions: 3.15 x 3.15 x 0.10 mm

Functional Block Diagram



General Description

TriQuint's TGP2107 is a 6-bit, digital phase shifter fabricated on TriQuint's high performance 0.15µm GaAs pHEMT process. It operates over 6 to 18 GHz and provides 360° of phase coverage with a LSB of 5.625°. It also achieves a low RMS phase error of 5° with 8 dB of insertion loss over all states.

The TGP2107 uses negative switch logic, eliminating the need for a reference voltage. That, along with low insertion and a high degree of resolution makes the TGP2107 ideally suited for a variety of wideband phased array applications, including commercial and military radars, satellite-based communication systems and electronic warfare.

The device is lead-free and RoHS compliant.

Pad Configuration

Pad No.	Symbol
1	RF In
2	90° Bit
3, 15	5N° Bit
4, 14	5P° Bit
5, 13	11N° Bit
6, 12	11P° Bit
7	180P° Bit
8	180N° Bit
9	45° Bit
10	22° Bit
11	RF Out

Ordering Information

Part	ECCN	Description
TGP2107	EAR99	6-Bit Digital Phase Shifter (-V_c)

Absolute Maximum Ratings

Parameter	Value
Control Voltage	6 V
Control Current	–15 to +5 mA
Power Dissipation	0.9 W
Input Power, CW, 50 Ω, 85°C	30 dBm
Channel tremperature	200°C
Mounting Temperature (30 Seconds)	320°C
Storage Temperature	–55 to 150°C

Operation of this device outside the parameter ranges given above may cause permanent damage. These are stress ratings only, and functional operation of the device at these conditions is not implied.

Recommended Operating Conditions

Parameter	Value
Control Votage (5N, 5P, 11N, 11P, 22, 45, 90, 180N, 180P)	–5/0 V

Electrical specifications are measured at specified test conditions. Specifications are not guaranteed over all recommended operating conditions.

Electrical Specifications

Test conditions unless otherwise noted: 25°C. Control Voltage (5N, 5P, 11N, 11P, 22, 45, 90, 180N, 180P) = −5/0 V; See Bias Truth Table.

Parameter	Conditions	Min	Typical	Max	Units
Operational Frequency Range		6		18	GHz
Insertion Loss			6 - 10		dB
Input Return Loss			>12		dB
Output Return Loss			>12		dB
RMS Phase Error			5		deg
RFM Amplitude Error			0.55		dB
Input P1dB			>25		dBm
Input IP3	Tone spacing = 10 MHz Pin/Tone = 15 dBm		>41		dBm
Insertion Loss Temperature Coefficient			0.008		dB/°C

Bias Truth Table

Logic “0” = –5 V, Logic “1” = 0 V

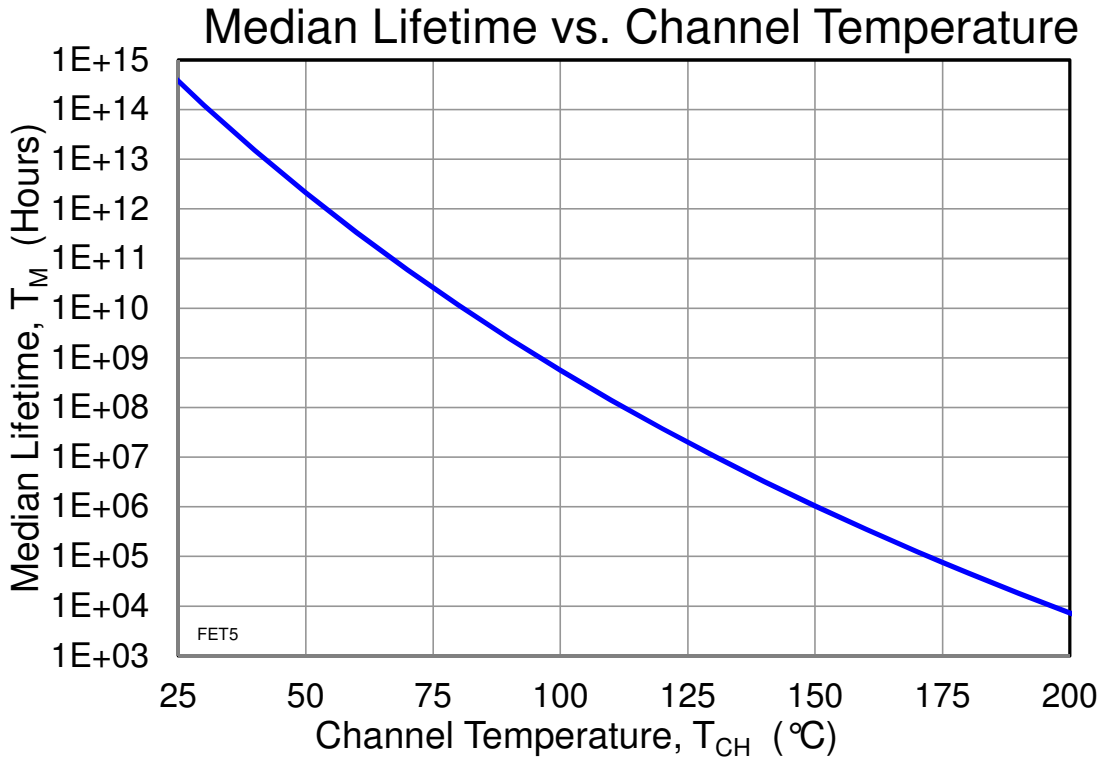
Phase Shifter	5P	5N	11P	11N	22	45	90	180P	180N
0° (Reference)	0	1	0	1	0	0	0	0	1
5°	1	0	0	1	0	0	0	0	1
11°	0	1	1	0	0	0	0	0	1
22°	0	1	0	1	1	0	0	0	1
45°	0	1	0	1	0	1	0	0	1
90°	0	1	0	1	0	0	1	0	1
180°	0	1	0	1	0	0	0	1	0
355°	1	0	1	0	1	1	1	1	0

Thermal and Reliability Information

Parameter	Test Conditions	Value	Units
Thermal Resistance (θ_{JC}) (1)	P_{DISS} = 0.09 W, $T_{BASEPLATE}$ = 85°C	22	°C/W
Channel Temperature (T_{CH})		87	°C
Median Lifetime (T_M)		3.8E+9	Hrs

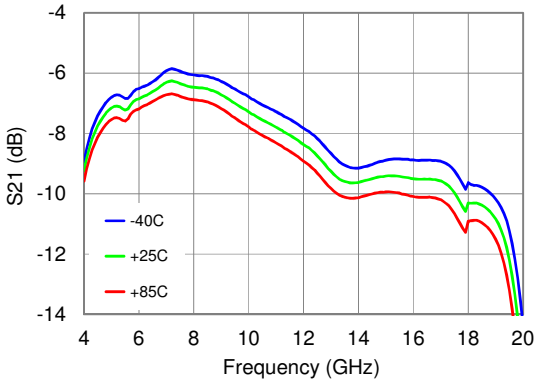
Notes:
1. Thermal resistance measured to back of carrier plate. MMIC mounted on 40 mils thick CuMo carrier using 1.5 mil 80/20 AuSn.

Median Lifetime

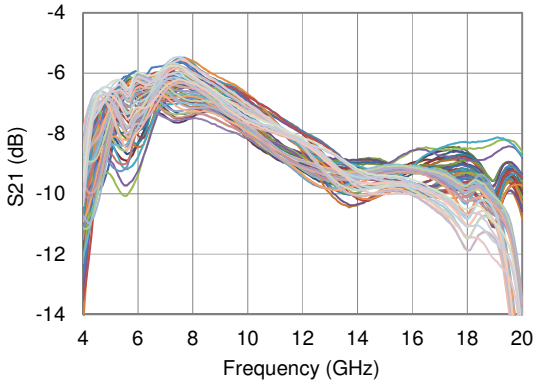


Typical Performance

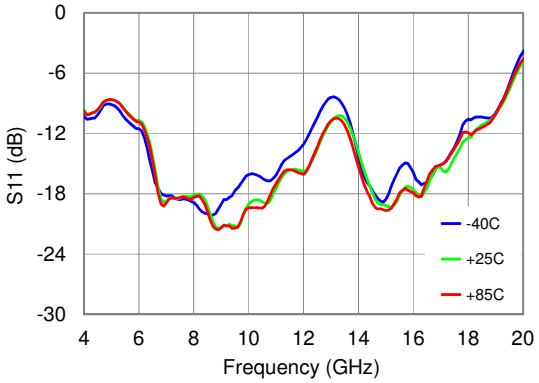
Average Insertion Loss vs. Temperature
All phase states



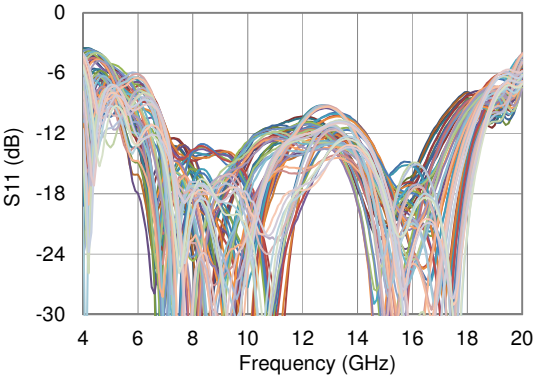
Insertion Loss vs. Frequency
All phase states



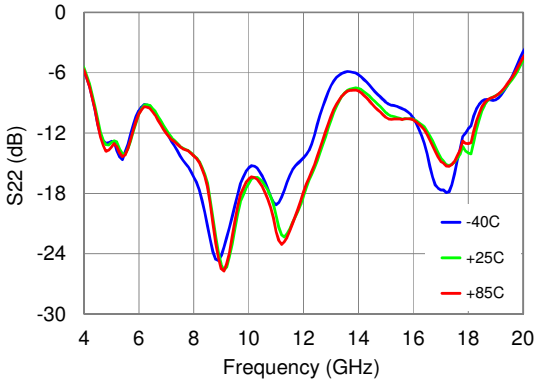
Average IRL vs. Temperature
All phase states



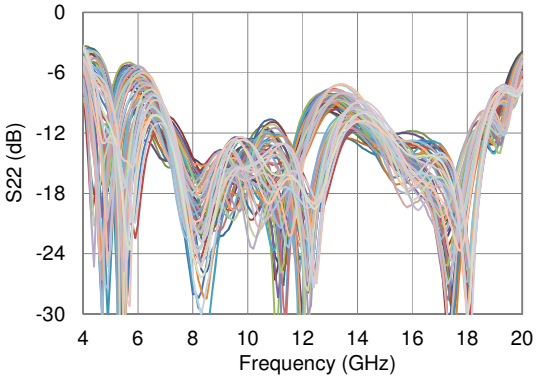
Input Return Loss vs. Frequency
All phase states, 25C



Average ORL vs. Temperature
All phase states

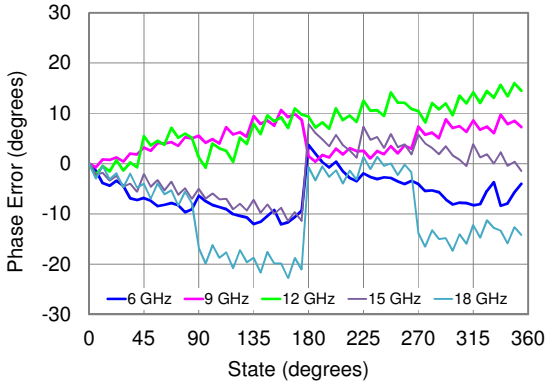


Output Return Loss vs. Frequency
All phase states, 25C

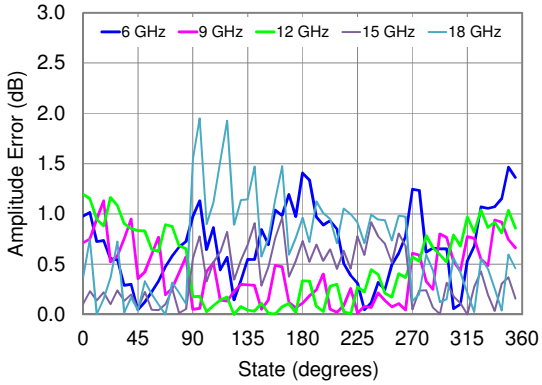


Typical Performance

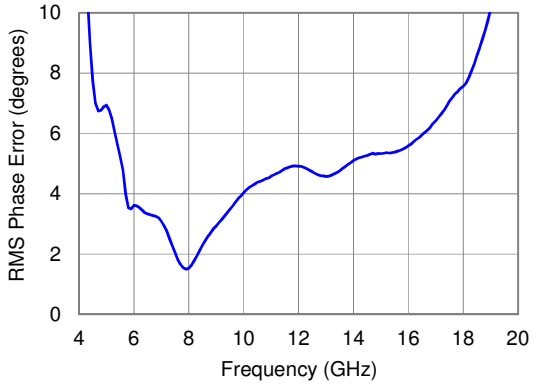
Phase Error vs. State
25C



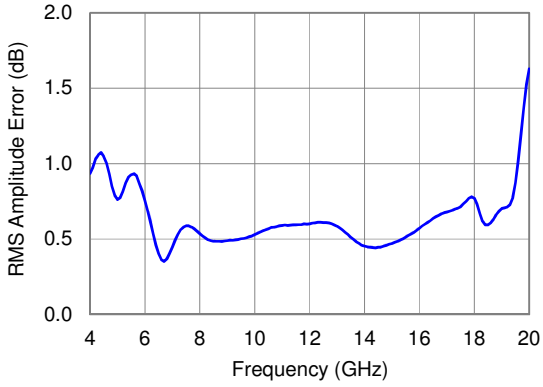
Amplitude Error (relative to mean)
25C



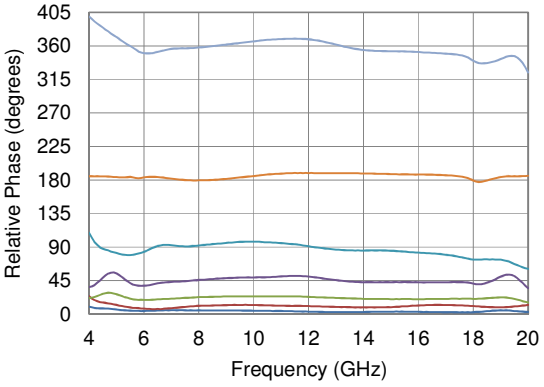
RMS Phase Error vs. Frequency
All phase states, 25C



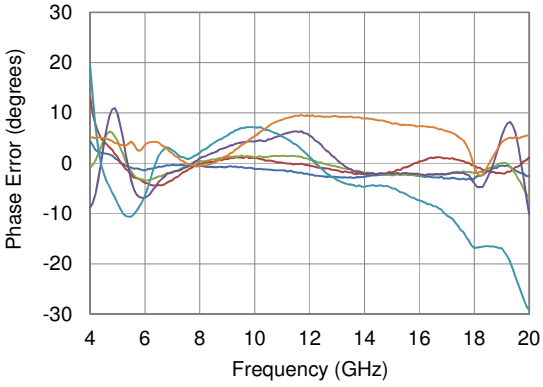
RMS Amplitude Error vs. Frequency
All phase states, 25C



Relative Phase Shift vs. Frequency
Major States, 25C

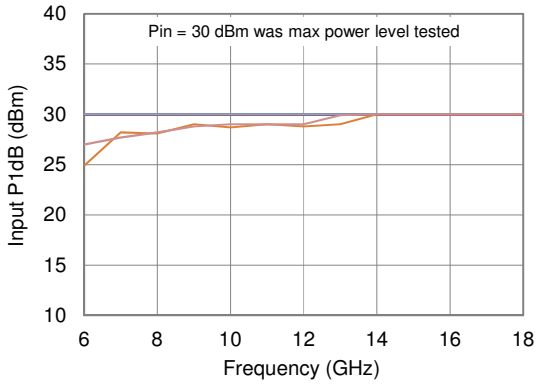


Phase Error vs. Frequency
Major States, 25C

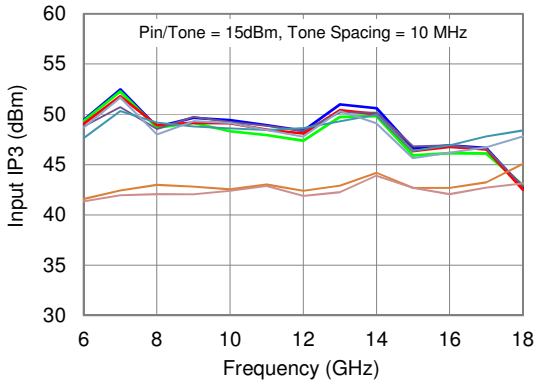


Typical Performance

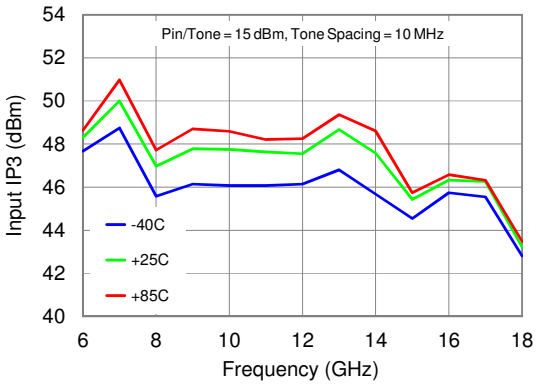
Input P1dB vs. Frequency
Major phase states, 25C



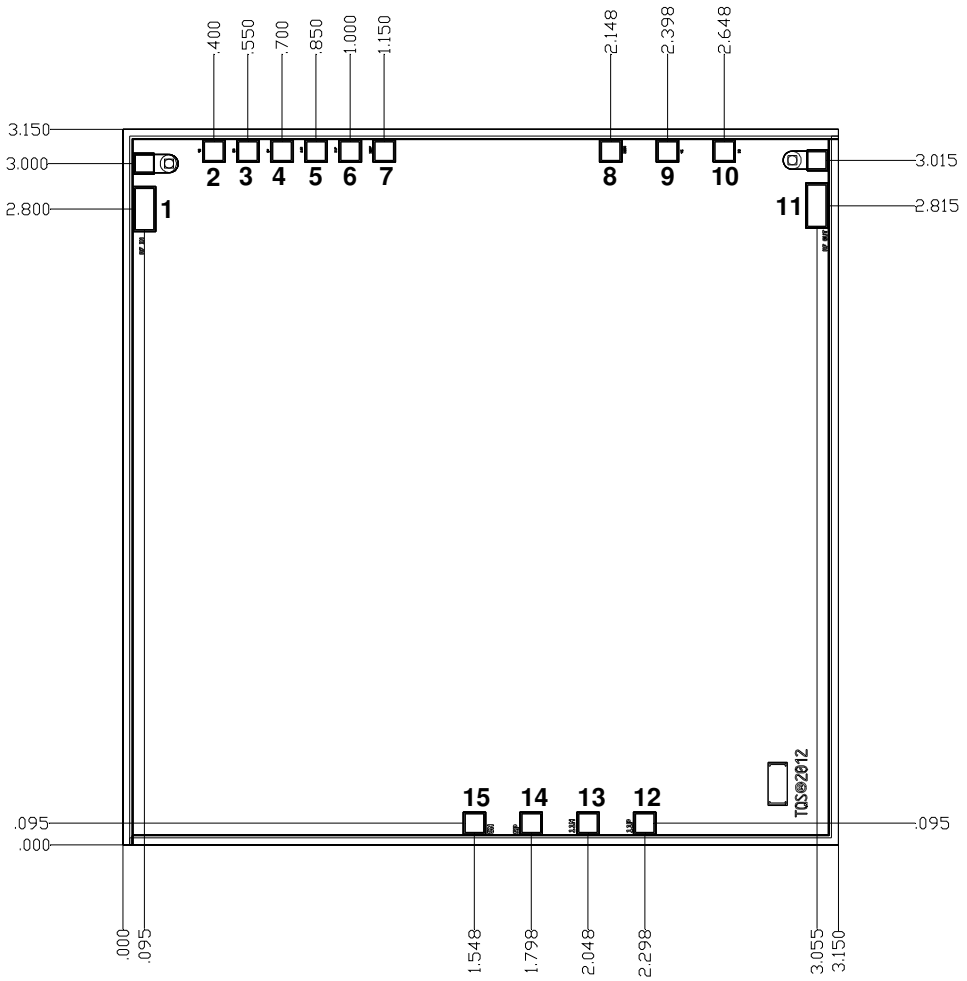
Input IP3 vs. Frequency
Major phase states, 25C



Input IP3 vs. Frequency vs. Temperature
REF States



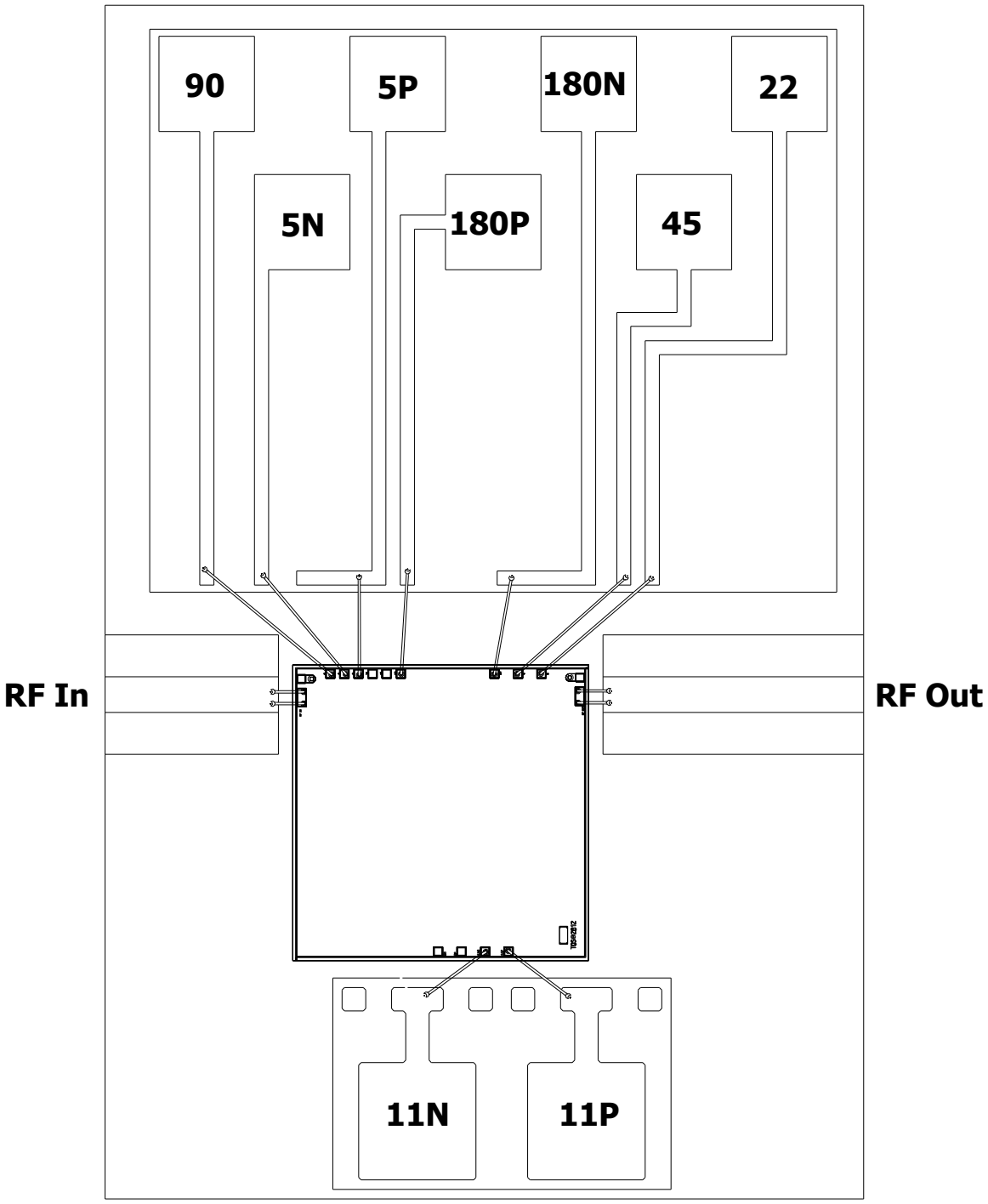
Mechanican Information and Bond Pad Description



Unit: millimeters
Thickness: 0.10
Die x, y size tolerance: ± 0.050
Chip edge to bond pad dimensions are shown to center of pad
Ground is backside of die

Bond Pad	Symbol	Description	Pad Size
1	RF In	Input; matched to 50 Ω; DC de-coupled	0.200 x 0.100
2	90	90° Bit	0.100 x 0.100
3, 12	5N	5N° Bit; use either pad 3 or 12	0.100 x 0.100
4, 13	5P	5P° Bit; use either pad 4 or 13	0.100 x 0.100
5, 14	11N	11N° Bit; use either pad 5 or 14	0.100 x 0.100
6, 15	11P	11P° Bit; use either pad 6 or 15	0.100 x 0.100
7	180P	180P° Bit	0.100 x 0.100
8	180N	180N° Bit	0.100 x 0.100
9	45	45° Bit	0.100 x 0.100
10	22	22° Bit	0.100 x 0.100
11	RF Out	Output; matched to 50 Ω; DC de-coupled	0.200 x 0.100

Assembly Drawing



- The spacing between MMIC and TFN (at RF In or RF Out) is <5 mils typical.
- RF connections: Bond two 1 mil diameter, <20 mils length gold bond wires at RF In and RF Out for optimum RF performance.

Assembly Notes

Component placement and adhesive attachment assembly notes:

- Vacuum pencils and/or vacuum collets are the preferred method of pick up.
- Air bridges must be avoided during placement.
- The force impact is critical during auto placement.
- Solder or Organic Adhesive attachment can be used for TGL2205.
- Curing should be done in a convection oven; proper exhaust is a safety concern.

Solder attachment reflow process assembly notes:

- Use AuSn (80/20) solder and limit exposure to temperatures above 300°C to 3 to 4 minutes, maximum.
- An alloy station or conveyor furnace with reducing atmosphere should be used.
- Do not use any kind of flux.
- Coefficient of thermal expansion matching is critical for long-term reliability.
- Devices must be stored in a dry nitrogen atmosphere.

Organic adhesive attachment assembly notes:

- The organics such as epoxy or polyimide can be used.
- Epoxies cure at temperatures of 100 to 200°C.

Interconnect process assembly notes:

- Thermosonic ball bonding is the preferred interconnect technique.
- Force, time, and ultrasonics are critical parameters.
- Aluminum wire should not be used.
    - Devices with small pad sizes should be bonded with 0.0007-inch wire.

Product Compliance Information

ESD Sensitivity Ratings

Caution! ESD-Sensitive Device

ESD Rating: TBD
Value: TBD
Test: Human Body Model (HBM)
Standard: JEDEC Standard JESD22-A114

Solderability

This part is compliant with EU 2002/95/EC RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment).

This product also has the following attributes:

- Lead Free
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A ($C_{15}H_{12}Br_4O_2$) Free
- PFOS Free
- SVHC Free

ECCN

US Department of Commerce: EAR99

Contact Information

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